

3A, 200V - 600V High Efficient Surface Mount Rectifier

FEATURES

- Very low profile, typical height of 1.1mm
- Excellent high temperature stability
- Glass passivated chip junction
- Controlled avalanche characteristics
- Low leakage current
- High forward surge capability
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

	_					_		_
	-	-	-	Α.	-	^		•
4	_		.IC	Д			м	-

- DC to DC converter
- Switching mode converters and inverters
- Freewheeling application

MECHANICAL DATA

- Case: TO-277A (SMPC)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- · Polarity: Indicated by cathode band
- Weight: 0.095g (approximately)

KEY PARAMETERS					
PARAMETER	VALUE	UNIT			
I _F	3	Α			
V_{RRM}	200 - 600	V			
I _{FSM}	50	Α			
T_{JMAX}	175	°C			
Package	TO-277A (SMPC)				
Configuration	Single die				

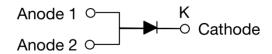








TO-277A (SMPC)



PARAMETER	SYMBOL	TPAU3D	TPAU3G	TPAU3J	UNIT	
Marking code on the device		AU3D	AU3G	AU3J		
Repetitive peak reverse voltage	V_{RRM}	200	400	600	V	
Reverse voltage, total rms value		V _{R(RMS)}	140	280	420	V
Forward current	I _F	3		Α		
Surge peak forward current, 8.3m sine wave superimposed on rated	I _{FSM}	50		Α		
Non-repetitive avalanche energy $I_{AS} = 2.5A \text{ Max}$ $I_{AS} = 1.0A \text{ Typ}$		L	20			mJ
		E _{AS}	30			mJ
Junction temperature	T _J	-55 to +175		°C		
Storage temperature	T _{STG}	-55 to +175		°C		



Taiwan Semiconductor

THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP	UNIT		
Junction-to-lead thermal resistance ⁽¹⁾	$R_{\Theta JL}$	6	°C/W		
Junction-to-ambient thermal resistance ⁽²⁾	$R_{\Theta JA}$	78	°C/W		

Notes:

- 1. Mounted on FR4 PCB with 16mm x 16mm Cu pad area
- 2. Free air, mounted on recommended pad

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT	
Forward voltage ⁽¹⁾	$I_F = 3A, T_J = 25^{\circ}C$	V	1.50	1.88	V	
Forward Vollage	I _F = 3A, T _J = 125°C	V_{F}	1.10	1.35	V	
Reverse current @ rated V _R ⁽²⁾	T _J = 25°C		-	10	μA	
Reverse current @ fated V _R	T _J = 125°C	- I _R	-	250	μA	
Junction capacitance	1MHz, V _R = 4.0V	C _J	60	-	pF	
Reverse recovery time	IF = 0.5A, IR = 1.0A Irr = 0.25A	t _{rr}	-	75	ns	

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION					
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING			
TPAU3x	TO-277A (SMPC)	6,000 / Tape & Reel			

Notes:

1. "x" defines voltage from 200V(TPAU3D) to 600V(TPAU3J)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

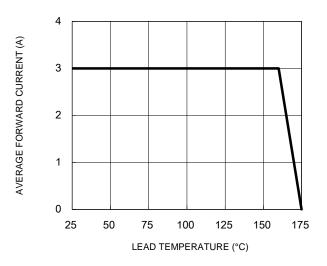


Fig.3 Typical Reverse Characteristics

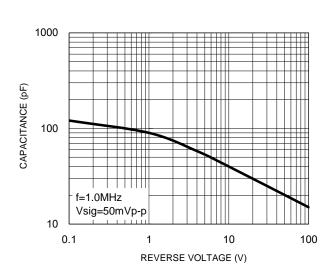
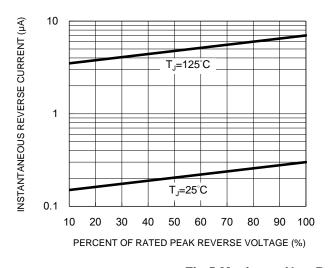


Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics



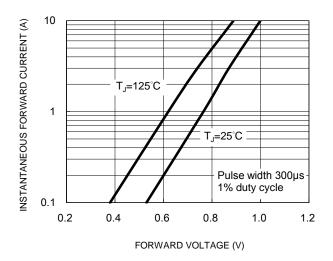
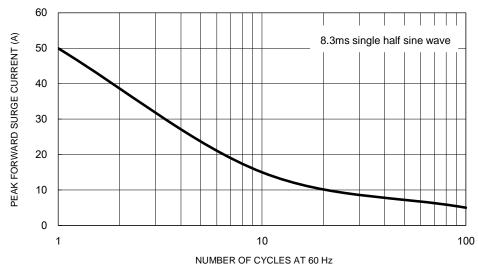


Fig.5 Maximum Non-Repetitive Forward Surge Current



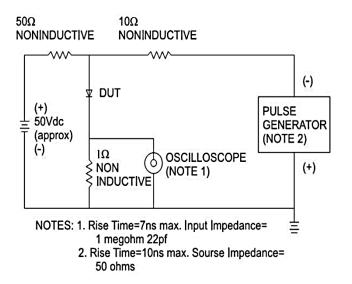
3

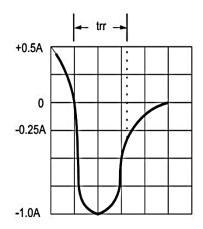


CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.6 Reverse Recovery Time Characteristic and Test Circuit Diagram

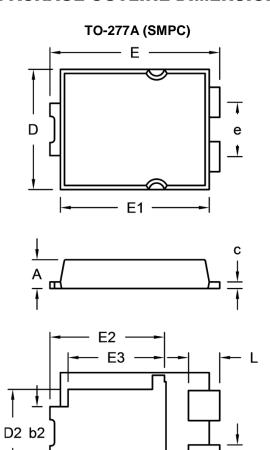






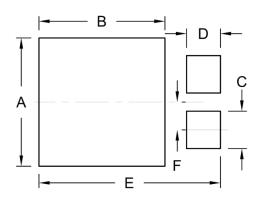


PACKAGE OUTLINE DIMENSIONS



DIM.	Unit	(mm)	Unit (inch)		
DIIVI.	Min.	Max.	Min.	Max.	
Α	1.000	1.200	0.039	0.047	
b	1.000	1.300	0.039	0.051	
b2	1.850	2.150	0.073	0.085	
С	0.175	0.325	0.007	0.013	
D	4.550	4.650	0.179	0.183	
D2	3.170	3.470	0.125	0.137	
E	6.350	6.650	0.250	0.262	
E1	5.650	5.750	0.222	0.226	
E2	4.235	4.535	0.167	0.179	
E3	3.540	3.840	0.139	0.151	
е	1.930	2.230	0.076	0.088	
L	1.043	1.343	0.041	0.053	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
А	4.80	0.189
В	4.72	0.186
С	1.40	0.055
D	1.27	0.050
E	6.80	0.268
F	1.04	0.041

MARKING DIAGRAM



P/N = Marking Code YW = Date Code F = Factory Code



Taiwan Semiconductor

Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf assumes no responsibility or liability for any errors or inaccuracies.

Purchasers are solely responsible for the choice, selection, and use of TSC products and TSC assumes no liability for application assistance or the design of Purchasers' products.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.